

REMARKS

Claims 1-17 are pending in the application. Of these, claims 1 and 13 have been amended to more clearly define the invention.

The drawings stand objected to. A submission of formal drawings accompanies this amendment. The formal drawings are believed to conform to the requirements of 37 C.F.R. § 1.184 (h)(3), and the objection to the drawings is believed to be overcome. Accordingly, withdrawal of the objection to the drawings is believed to be in order.

Claims 13-17 stand rejected under 35 U.S.C. § 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which Applicant regards as the invention. Claim 13 has been amended to overcome the rejection. In particular the amendment clarifies the position of the metal contact. Accordingly, the rejection under 35 U.S.C. § 112, second paragraph, of claims 13, and claims 14-17 which depend therefrom, is believed to be overcome.

Claims 1-17 stand rejected under 35 U.S.C. § 102 (e) as being anticipated by United States patent number 6,475,824 to Kim (Kim). As discussed in an amendment filed on March 4, 2003 the present invention relates to a frame scale package using contact lines through the elements. Claim one recites, *inter alia*, the limitations of "a frame having a top surface and a bottom surface, said bottom surface including an indented area ... and a contact portion... extending along said bottom surface within said indented area, and...within [a] non indented area." This combination of limitations is not taught or suggested in the prior art, including the Kim reference. In particular, the Kim reference does not show, and would not lead one of skill in the art to, "a contact portion... extending... within [a] non indented area." Accordingly, the rejection of claim 1 under 35 U.S.C. § 102 (e) over Kim is believed to be overcome. Withdrawal of the pending rejection and allowance of claim 1 is therefore respectfully solicited.

Claims 2-12 each depend, directly or indirectly, from claim 1 and incorporate every limitation thereof. Accordingly, the rejection of claims 2-12 under 35 U.S.C. § 102 (e) over Kim are overcome for at least the reasons given above in relation to claim 1.

Claim 13 recites:

A package for an integrated circuit, comprising: a packaging portion having a first bottom surface with an outer perimeter and an inner perimeter, said inner perimeter being disposed at an intersection of said first bottom surface with an inward facing surface, said packaging portion having a second bottom surface within said inner perimeter, said first bottom surface, said inward facing surface, and said second bottom surface mutually having a metal contact thereon, said metal contact being adapted to connect to an integrated circuit disposed within said inward facing surface. (Emphasis added).

Kim does not teach or suggest the unique combination of limitations of claim 13, including a first bottom surface, and inward facing surface, and a second bottom surface, " said first bottom surface, said inward facing surface, and said second bottom surface mutually having a metal contact thereon." Accordingly, Kim does not anticipate claim 13, or render it obvious, and the rejection of claim 13 under 35 U.S.C. § 102 (e) over Kim is overcome.

Claims 14-17 each depend, directly or indirectly, from claim 13 and incorporate every limitation thereof. Accordingly, the rejection of claims 14-17 under 35 U.S.C. § 102 (e) over Kim are overcome for at least the reasons given above in relation to claim 13.

In view of the above, each of the presently pending claims in this application is believed to be in immediate condition for allowance. Accordingly, the Examiner is respectfully requested to pass this application to issue.

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Respectfully submitted,

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